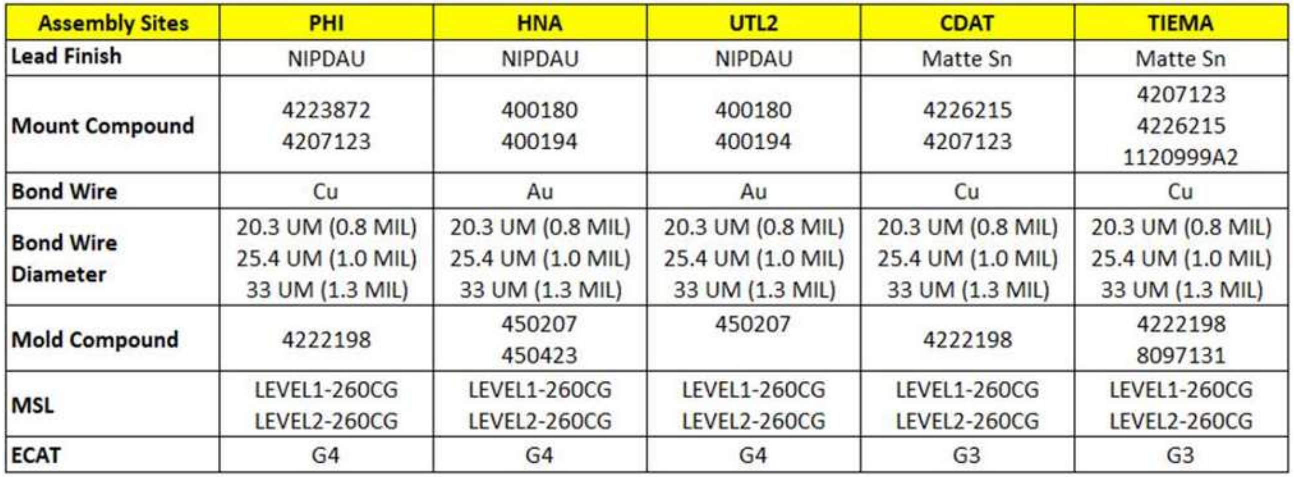
PCN20230327005.1補足

Pls refer below as an update on this inquiry, thanks.

PCN20230327005 Group 1



Assembly Sites	PHI	HNA	UTL2	CDAT	TIEMA
Lead Finish	NIPDAU	NIPDAU	NIPDAU	Matte Sn	Matte Sn
Mount Compound	4223872 4207123	400180 400194	400180 400194	4226215 4207123	4207123 4226215 1120999A2
Bond Wire	Cu	Au	Au	Cu	Cu
Bond Wire Diameter	20.3 UM (0.8 MIL) 25.4 UM (1.0 MIL) 33 UM (1.3 MIL)	20.3 UM (0.8 MIL) 25.4 UM (1.0 MIL) 33 UM (1.3 MIL)	20.3 UM (0.8 MIL) 25.4 UM (1.0 MIL) 33 UM (1.3 MIL)	20.3 UM (0.8 MIL) 25.4 UM (1.0 MIL) 33 UM (1.3 MIL)	20.3 UM (0.8 MIL) 25.4 UM (1.0 MIL) 33 UM (1.3 MIL)
Mold Compound	4222198	450207 450423	450207	4222198	4222198 8097131
MSL	LEVEL1-260CG LEVEL2-260CG	LEVEL1-260CG LEVEL2-260CG	LEVEL1-260CG LEVEL2-260CG	LEVEL1-260CG LEVEL2-260CG	LEVEL1-260CG LEVEL2-260CG
ECAT	G4	G4	G4	G3	G3

PCN20230327005 Group 2

Assembly Sites	PHI	HNA	UTL2	JCETJY/C8	CDAT	TIEMA
Lead Finish	NIPDAU	NIPDAU	NIPDAU	Matte Sn	Matte Sn	Matte Sn
Mold Compound	4222198	450207 450423	450207	120800005407	4222198	4222198 8097131
MSL	LEVEL1-260CG	LEVEL1-260CG	LEVEL1-260CG	LEVEL1-260CG	LEVEL1-260CG	LEVEL1-260CG
ECAT	G4	G4	G4	G3	G3	G3